







Adjustable Workstation

Series 6600 workstations are adjustable via a hand crank or motorized drive mechanism. With a weight capacity of 1000 lbs. and a height adjustment range of 15.5", workstations are available in sizes from 24 x 30" to 48 x 90". Center justified frames permit two operators to use the station simultaneously, increase work area and stabilize the station under heavy loads.

Arlink, arlink.com

Booth 1919

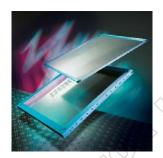


Pb-Free Solder

Multicore LF320 lead-free solder paste requires a minimum peak reflow temperature of 229°C. Is said to have a print speed of 25 to 100 mms⁻¹ and an abandon time of up to two hours. Reportedly resists slump and solder balling. Optimized for reflow in air; profiles may be extended with nitrogen.

Henkel Technologies, loctite.com/electronics

Booth 5024



Variable Foil Stencils

VectorGuard frame mounted stencils are surrounded by a thin aluminum extrusion, to reduce weight and sharp edges. Mounting requires no alignment of teeth, slots or holes. Rigid construction protects stencil body during handling and permits stencils to be washed as soon as they are removed from the frame, without requiring a washing jig.

DEK Intl., dek.com

Booth 5830



'No Calibration' Hand Tool

The PS-800 hand soldering tool features variable power/fixed temperature control and reportedly requires no calibration. Uses easy-to-remove replaceable heater tips. Designed for repetitive manual assembly and touch-up.

OK Intl., okinternational.com

Booth 5236



Reflow Performance Monitor

Datapaq Surveyor identifies if a process is within specific tolerances. This add-on to the reflow tracker system pinpoints where the reflow profile is out of tolerance. Adjustable frame rides on the oven rail or mesh belt and fixed temperature sensors closely mimic PCB behavior.

Datapaq Inc., datapaq.com

Booth 5807

High-Speed Robot

The TH650 SCARA robot reaches a composite max. speed of 7500 mm/s (z-axis 2000 mm/s), and fits into compact production cells. It has arm spans of 650 mm, a maximum payload of 10 kg and x- and y-axis repeatability of ± 0.015 mm. Reportedly can be integrated into applications requiring vision systems.

Toshiba Machine Co., toshiba-machine.com

Booth 3727

Diaphragm Valve

The TS5622VU-DVD diaphragm valve precisely dispenses low- to medium-viscosity fluids. The stainless steel fluid chamber is compatible with a range of chemicals and UV-cure fluids. A short opening stroke provides fast, positive shutoff. Has an external stroke control adjustment for finetuning shot sizes.

 ${\bf Techcon\ Systems,\ techcon systems.com}$

Booth 355

Modular X-Ray Platform

Cougar is a basic modular x-ray inspection platform. Initial configuration includes a microfocus x-ray tube up to 160 kV, TXI control, four-axes manipulator, a real-time image processing system and a real-time image chain with high-res 4" image intensifier and flat-screen monitor.

Feinfocus, feinfocus.com

Booth 5100

Post-Reflow Cleaner

Aquanox A4520 cleaning solvent helps clean reflowed no-clean flux residues in aqueous batch or in-line spray machines. Effective on reflowed paste and uncured SMD adhesives, is environmentally safe and protects solder joint/bumps from oxidation.

Kyzen Corp., kyzen.com

Booth 5206









Large Format Pick-and-Place

Over 300 feeders can be installed simultaneously on the CLM9000-PLUS-L pick-and-place machine for quick changeovers and complex assembly. Standard board size of 700 x 600 mm is expandable to 750 x 650 mm with 150 feeder slots. Based on a new software and hardware platform, mechanical improvements include a new drive system for faster placement.

Essemtec USA, essemtec-usa.com

Booth 5900



Real-Time X-Ray

The Verifier FSX-080 BGA/SMT solder verification and defect detection tool has a 30 x 33" footprint. Reportedly provides continuous real-time x-ray solder verification, defect detection and failure analysis of assemblies up to $16 \times 18^{\circ}$.

FocalSpot Inc., focalspot.com

Booth 5300



PCB Cleaner

Nikko Power Cyclone, a PCB cleaner with conveyor, thoroughly removes dust and particles from PCB surfaces before solder application. Combines brush, high-pressure air knife and vacuum removal.

NIX of America, nixofamerica.com

Booth 5404



Optical Inspection System

ERSASCOPE2 SMT/BGA inspection system offers an aperture height below 0.012 mm and is for lead-free PCB inspection. Provides 90° and side-view images of SMDs. Special flip-chip head reportedly provides a "look down image" of a flip chip with a standoff (gap) height of 0.050 mm.

ERSA Inc., ersa.com

Booth 5507



Manufacturing Production Monitor

TraceXpert MES (manufacturing execution system) enhances productivity and quality in SMT production. Includes real-time feeder and performance monitoring, automatic program selection, low level warning, stock control, traceability, feeder maintenance, kitting area optimization and MSD control.

Valor Computerized Systems Inc., valor.com

Booth 5138

Wafer Bumping Paste

SE-Cure 7501 solder paste for organic *in situ* wafer bumping applications prints on wafers of bump pitches below 125 μ m. Available in Sn63Pb37, as well as low alpha and ultra-low alpha Sn63Pb37, and is said to offer consistent printing, voiding occurrence rates below 10% and easy-to-strip post-reflow residues.

Kester, kester.com

Booth 5004

3-Head Pin Inserter

The P350 fully automatic x-y insertion machine applies terminals for PCBs with three product-specific insertion heads. Each head has a rotary insertion finger to apply products at different angles without rotating the PCB. Comes with transfer belts for inline operation, can insert up to 350 pins per min., has a maximum insertion area of 600 x 400 mm and features 0.02 mm repeatability.

Tyco Electronics, tycoelectronics.com

Booth 5439

Preforms for Pb-Free

Solder preforms, clad to various other metals, can be produced in a range of shapes and solder alloys, including lead-free. Solder can be clad onto one or both sides of the base material to produce rigid links, jumper discs and other structural items. Coppercored preforms are also available.

Indium Corp., indium.com

Booth 563

Benchtop Dispenser

DispenseMate D-550 benchtop dispenser is for batch operations, rework and process development. Features include a precision motion system with closed-loop brushless DC motors, an integrated height sensor, digital gauges and optional vision system.

Asymtek, asymtek.com

Booth 5414





Color AOI

ScanPoint color AOI operates before and after reflow, after paste disposition and inspects PCBs for component and solder faults. Easily programmed, with or without CAD data, it reportedly performs fast, comprehensive inspection. Available in desktop configuration or with SMEMA-compatible conveyor.

DiagnoSys Systems, diagnosys-usa.com

Booth 5817

Fine-Pitch Stencil Roll

Micro-Wipe FP roll wipe for fine-pitch screen printing, features a synthetic wiping fabric said to be stronger, more absorbent and cleaner than standard rolls. Is configured for all major stencil printers.

Micro Care, microcare.com

Booth 1061

Linear Magazine Feeder

Agilis magazines, for 8-, 12- and 16-mm feeders, use solenoid actuated feeder heads on servo-controlled linear motion mechanisms. Control speed, pitch and x/y positioning throughout pick cycle. Individual smart feeders can be loaded in 10 sec. or less and mounted in any position on the machine.

Mydata Automation Inc., mydata.com

Booth 5834

Bath Test Kit

The Easy Bath Control Kit eliminates tedious bath control measurements. Formulated for water-based cleaners, and said to eliminate hardware, calculations, indicator liquids and human error by requiring only a count of the number of drops of test liquid.

Zestron America, zestron.com

Booth 5408

Z-Axis Compliant Pin

Z-axis compliant pins, designed for automation using existing pick-and-place equipment with a special feeder, provide axial compliancy to compensate for thermal expansion and contraction. Benefits include geographical stability, high locational tolerances and the ability to randomly place individual pins. Can be placed on 0.100 x 0.120" on-center applications, ideal for parallel PCB stacking.

Zierick Manufacturing Corp., zierick.com

Booth 5017



Fine-Pitch Programmer

3700 MK2 provides automated fine-pitch programming for high-density flash up to 256Mb with programming times from 15 to 120 sec. and support for over 17,000 devices. It has 16 sockets using FX4 socket modules or universal programming with four standard socket modules. The system programs at 0.24 s/Mb, has a small footprint and full-time vision centering.

BP Microsystems, bpmicro.com

Booth 5335





High-Mix Screen Printer

MPM Accuflex stencil printer is for moderate volume, high-mix operations, handles boards from 3 x 2" to 23 x 20" and can print 0.012" devices. A triple-track conveyor system with 3 mm bottom-side edge clearance provides improved board flow and integration flexibility. The tooling system, programmable stencil positioning and off-line recipe programming increase uptime.

Speedline Technologies, speedlinetech.com

Booth 5809

Send your product releases to Robin Norvell at rnorvell@upmediagroup.com.